

# HSP

**NOTES:**

Current Rating: 3.0AMP  
 Withstand Voltage: 500V AC/DC  
 Contact Resistance: 20mΩ Max  
 Insulation Resistance: 1000MΩMin  
 Operation Temperature: -40°C to +105°C

Contact Material: Phosphor Bronze or Brass  
 Contact plating: Au or Sn over Ni  
 Insulator Material: PA6T or PBT+30%G.F UL94V-0

## Ordering Information

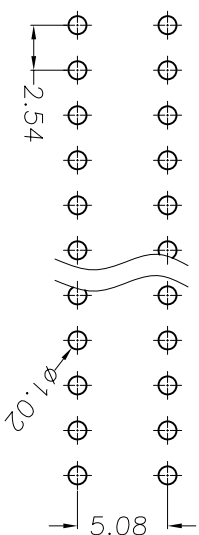
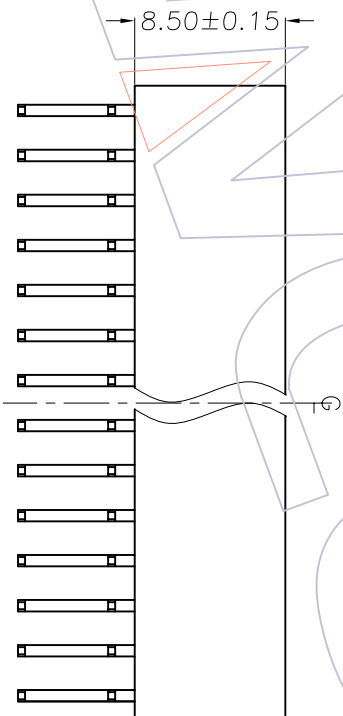
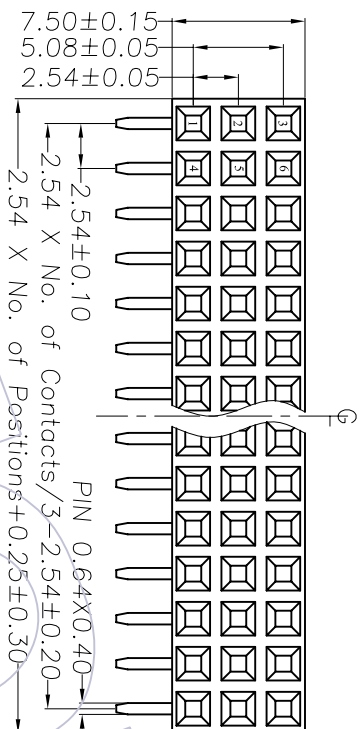
2185 - 3 XX R XX X YN T 2

No. of Pins per Row: 02~40PIN

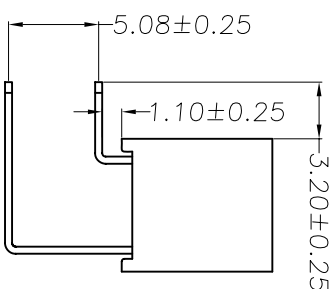
Contact Plating:  
 GP=Gold Flash  
 G1=5μ"Gold  
 G2=5μ"Gold  
 G3=10μ"Gold  
 G4=15μ"Gold  
 G5=30μ"Gold  
 SP=Gold Flash/Tin  
 S1=3μ"Gold/Tin  
 S2=5μ"Gold/Tin  
 S3=10μ"Gold/Tin  
 S4=15μ"Gold/Tin  
 S5=30μ"Gold/Tin  
 SN=Tin

Insulator:  
 A=PBT  
 C=PA6T

Packing:  
 T=Tube  
 A=Tray



Recommended P.C.B Layout(TOP Side)  
 (PCB BOARD TOLERANCE±0.05)



OPERATION		DRAW		SCALE		PART NO.	
XXX	±0.40	DESIGN	UNIT	mm	A4	2185-3XXXXXXYT2	
XXX	±0.25	CHECK	SIZE	1/1	SHEET	TITLE:	
Angle	± 3'	APPROVE	PROJ.	Customer NO.	FH2.54mm THREE ROWS 90° H=8.5		
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE			
A0	08/03/13	NEW					
1							

**WCON** 维峰五金电子有限公司  
 WAFER HARDWARE ELECTRONICS CO.,LTD